

### FEATURES

- 10µs Short Circuit Withstand
- Non Punch Through Silicon
- Isolated Copper Baseplate

### APPLICATIONS

- Matrix Converters
- Brushless Motor Controllers
- Frequency Converters

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 600V to 3300V and currents up to 3600A.

The DIM200MBS12-A000 is a bi-directional 1200V, n channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus full 10µs short circuit withstand.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

### ORDERING INFORMATION

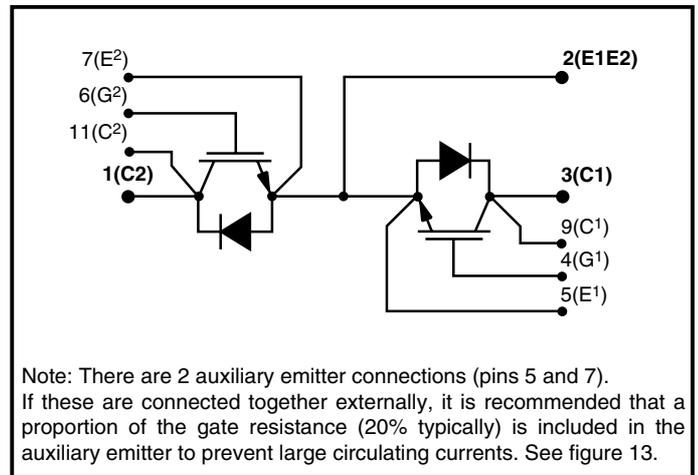
Order As:

**DIM200MBS12-A000**

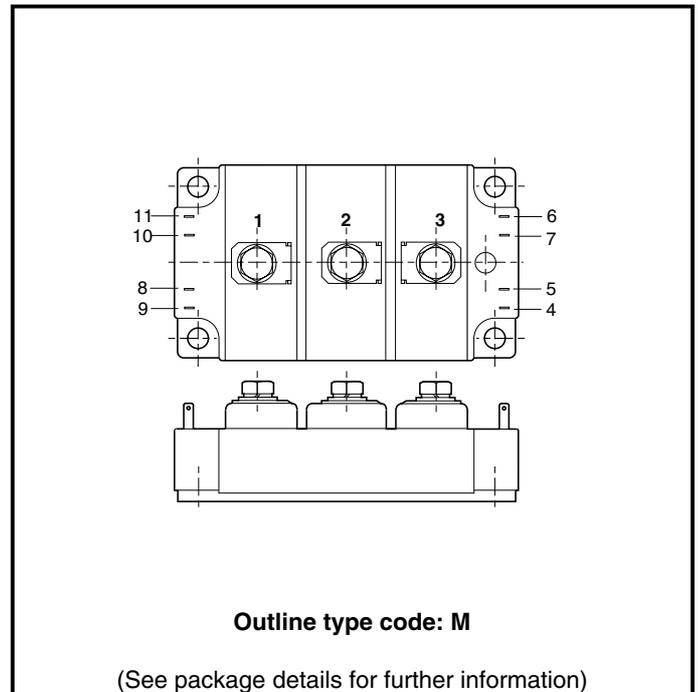
Note: When ordering, please use the whole part number.

### KEY PARAMETERS

$V_{DRM}$		$\pm 1200V$
$V_T$	(typ)	4.3V
$I_C$	(max)	200A
$I_{C(PK)}$	(max)	400A



**Fig. 1 Bi-directional switch circuit diagram**



**Fig. 2 Electrical connections - (not to scale)**

## ABSOLUTE MAXIMUM RATINGS - PER ARM

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
$V_{DRM}$	Collector-emitter voltage (measured across terminals 2 and 3)	$V_{GE} = 0V$	1200	V
$V_{GES}$	Gate-emitter voltage	-	$\pm 20$	V
$I_C$	Continuous collector current	$T_{case} = 80^{\circ}\text{C}$	200	A
$I_{C(PK)}$	Peak collector current	1ms, $T_{case} = 115^{\circ}\text{C}$	400	A
$P_{max}$	Max. transistor power dissipation	$T_{case} = 25^{\circ}\text{C}$ , $T_j = 150^{\circ}\text{C}$	1435	W
$I^2t$	Diode $I^2t$ value	$V_R = 0$ , $t_p = 10\text{ms}$ , $T_{vj} = 125^{\circ}\text{C}$	6.25	$\text{kA}^2\text{s}$
$V_{isol}$	Isolation voltage - per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	2500	V
$Q_{PD}$	Partial discharge - per module	IEC1287. $V_1 = 1300V$ , $V_2 = 1000V$ , 50Hz RMS	10	PC

**THERMAL AND MECHANICAL RATINGS**

Internal insulation:  $\text{Al}_2\text{O}_3$   
 Baseplate material: Cu  
 Creepage distance: 22mm  
 Clearance: 12mm  
 CTI (Critical Tracking Index): 175

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - transistor (per arm)	Continuous dissipation - junction to case	-	-	87	$^{\circ}\text{C}/\text{kW}$
$R_{th(j-c)}$	Thermal resistance - diode (per arm)	Continuous dissipation - junction to case	-	-	194	$^{\circ}\text{C}/\text{kW}$
$R_{th(c-h)}$	Thermal resistance - case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	15	$^{\circ}\text{C}/\text{kW}$
$T_j$	Junction temperature	Transistor	-	-	150	$^{\circ}\text{C}$
		Diode	-	-	125	$^{\circ}\text{C}$
$T_{stg}$	Storage temperature range	-	-40	-	125	$^{\circ}\text{C}$
-	Screw torque	Mounting - M6	-	-	5	Nm
		Electrical connections - M4	-	-	2	Nm

## ELECTRICAL CHARACTERISTICS

 $T_{case} = 25^{\circ}\text{C}$  unless stated otherwise.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}$	-	-	0.25	mA	
		$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_{case} = 125^{\circ}\text{C}$	-	-	6	mA	
$I_{GES}$	Gate leakage current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}$	-	-	1	$\mu\text{A}$	
$V_{GE(TH)}$	Gate threshold voltage	$I_C = 10\text{mA}, V_{GE} = V_{CE}$	4.5	5.5	6.5	V	
$V_{CE(sat)}^{\dagger}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{V}, I_C = 200\text{A}$	-	2.2	2.6	V	
		$V_{GE} = 15\text{V}, I_C = 200\text{A}, T_{case} = 125^{\circ}\text{C}$	-	2.6	3.0	V	
$V_T$	On-state voltage (measured across terminals 2 and 3)	$V_{GE} = 15\text{V}, I_C = 200\text{A}$	-	4.3	5.0	V	
		$V_{GE} = 15\text{V}, I_C = 200\text{A}, T_{case} = 125^{\circ}\text{C}$	-	4.7	5.4	V	
$I_F$	Diode forward current	DC	-	-	200	A	
$I_{FM}$	Diode maximum forward current	$t_p = 1\text{ms}$	-	-	400	A	
$V_F^{\dagger}$	Diode forward voltage	$I_F = 200\text{A}$	-	2.1	2.4	V	
		$I_F = 200\text{A}, T_{case} = 125^{\circ}\text{C}$	-	2.1	2.4	V	
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	23	-	nF	
$L_M$	Module inductance - per arm	-	-	30	-	nH	
$R_{INT}$	Internal transistor resistance - per arm	-	-	0.27	-	m $\Omega$	
$SC_{Data}$	Short circuit. $I_{SC}$	$T_j = 125^{\circ}\text{C}, V_{CC} = 900\text{V},$	$I_1$		1375	-	A
		$t_p \leq 10\mu\text{s}, V_{CE(max)} = V_{CES} - L^* \cdot di/dt$ IEC 60747-9	$I_2$		1125	-	A

**Note:**
 $\dagger$  Measured at the power busbars and not the auxiliary terminals)

 $L^*$  is the circuit inductance +  $L_M$

**ELECTRICAL CHARACTERISTICS**
**T<sub>case</sub> = 25°C unless stated otherwise**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
t <sub>d(off)</sub>	Turn-off delay time	$I_C = 200A$ $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$ $L \sim 100nH$	-	600	-	ns
t <sub>f</sub>	Fall time		-	50	-	ns
E <sub>OFF</sub>	Turn-off energy loss		-	20	-	mJ
t <sub>d(on)</sub>	Turn-on delay time		-	240	-	ns
t <sub>r</sub>	Rise time		-	95	-	ns
E <sub>ON</sub>	Turn-on energy loss		-	25	-	mJ
Q <sub>g</sub>	Gate charge		-	2	-	μC
Q <sub>rr</sub>	Diode reverse recovery charge	$I_F = 200A, V_R = 600V,$ $di_F/dt = 2100A/\mu s$	-	30	-	μC
I <sub>rr</sub>	Diode reverse current		-	125	-	A
E <sub>REC</sub>	Diode reverse recovery energy		-	13	-	mJ

**T<sub>case</sub> = 125°C unless stated otherwise**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
t <sub>d(off)</sub>	Turn-off delay time	$I_C = 200A$ $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$ $L \sim 100nH$	-	800	-	ns
t <sub>f</sub>	Fall time		-	70	-	ns
E <sub>OFF</sub>	Turn-off energy loss		-	27	-	mJ
t <sub>d(on)</sub>	Turn-on delay time		-	385	-	ns
t <sub>r</sub>	Rise time		-	110	-	ns
E <sub>ON</sub>	Turn-on energy loss		-	40	-	mJ
Q <sub>rr</sub>	Diode reverse recovery charge	$I_F = 200A, V_R = 600V,$ $di_F/dt = 1900A/\mu s$	-	50	-	μC
I <sub>rr</sub>	Diode reverse current		-	140	-	A
E <sub>REC</sub>	Diode reverse recovery energy		-	20	-	mJ

TYPICAL CHARACTERISTICS

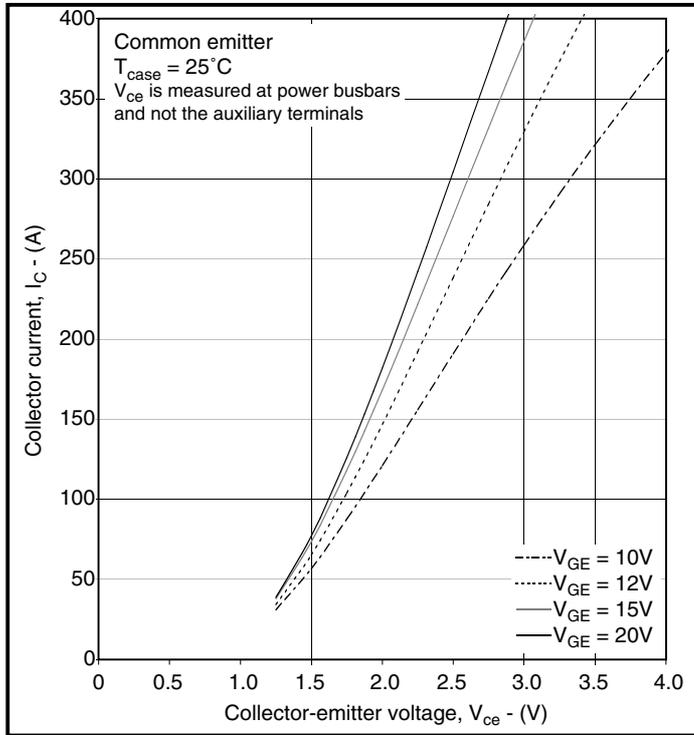


Fig. 3 Typical output characteristics

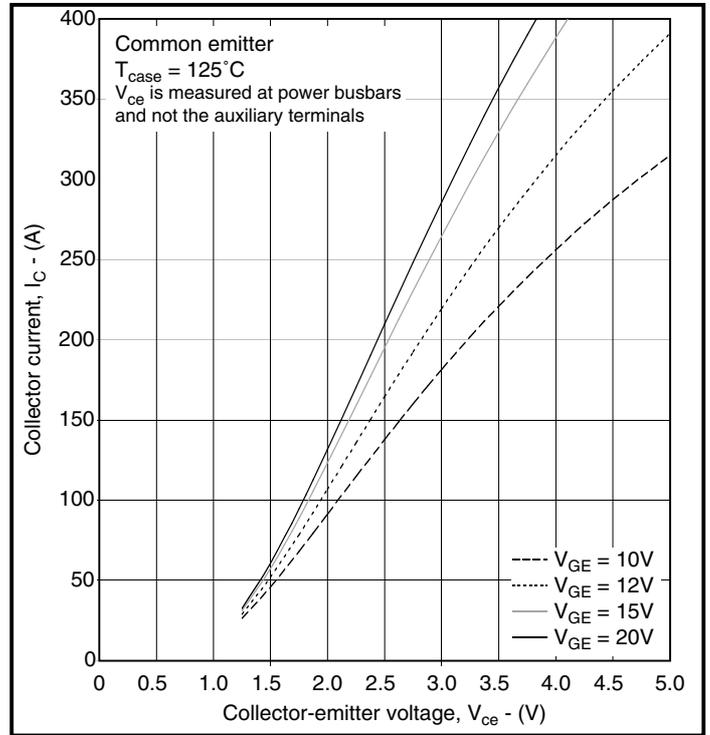


Fig. 4 Typical output characteristics

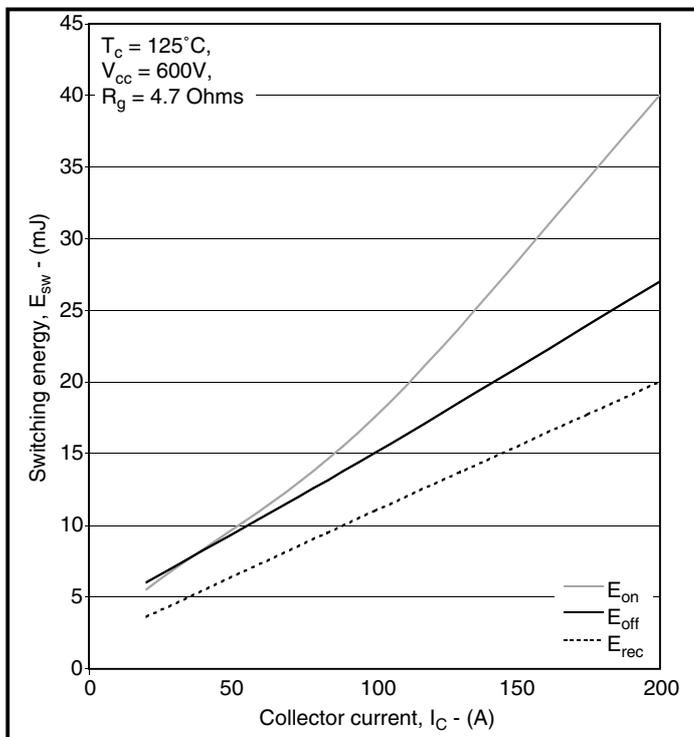


Fig. 5 Typical switching energy vs collector current

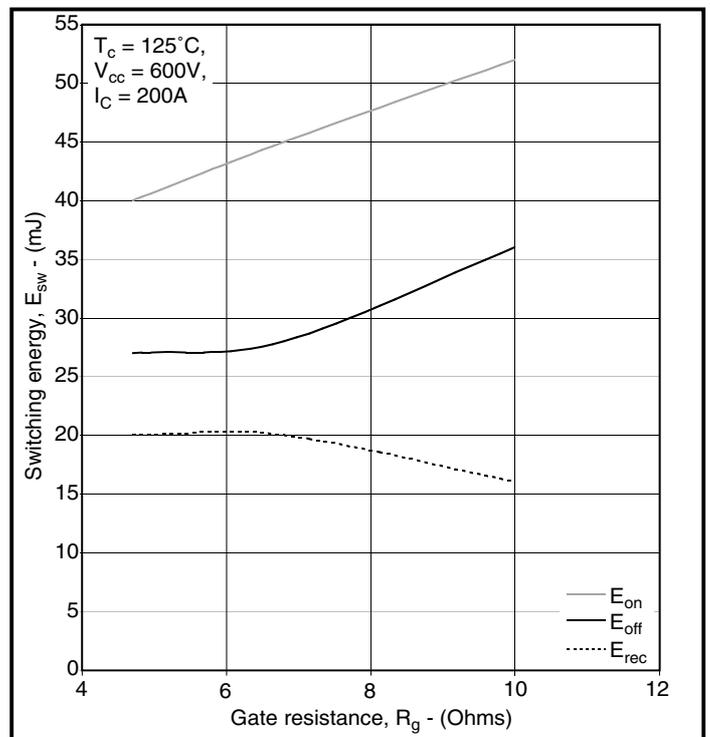
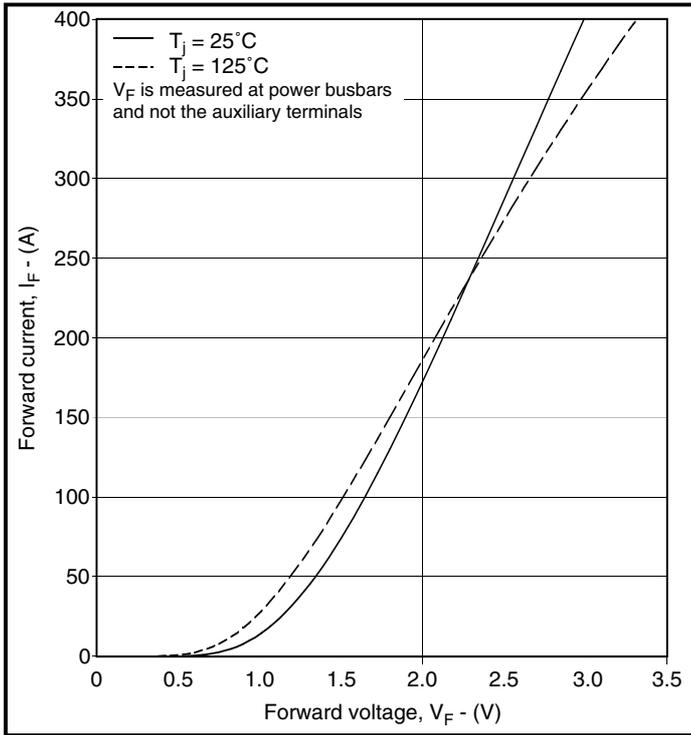
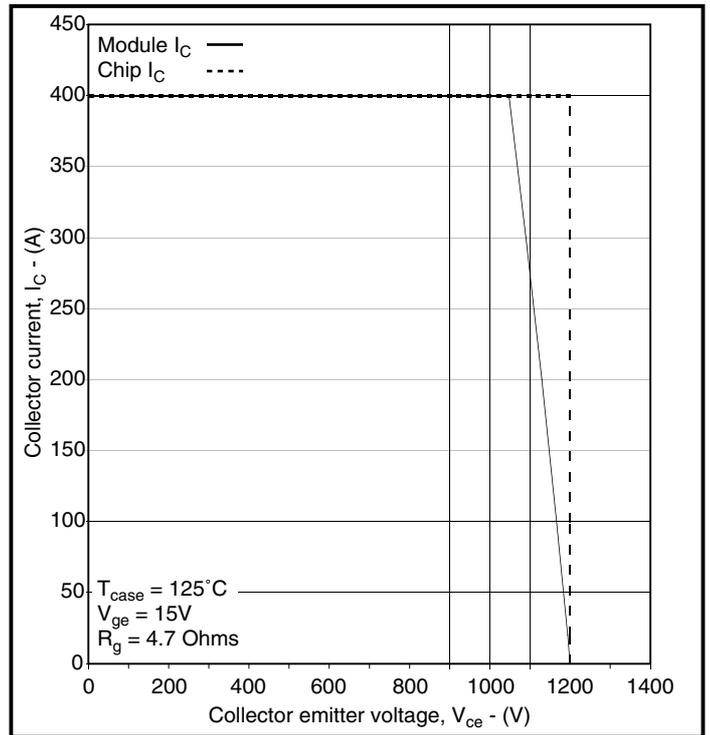
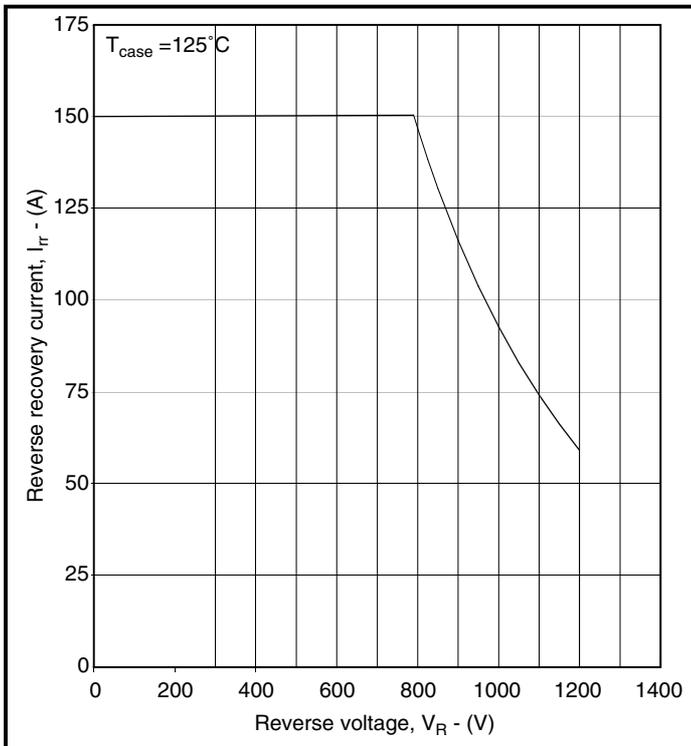
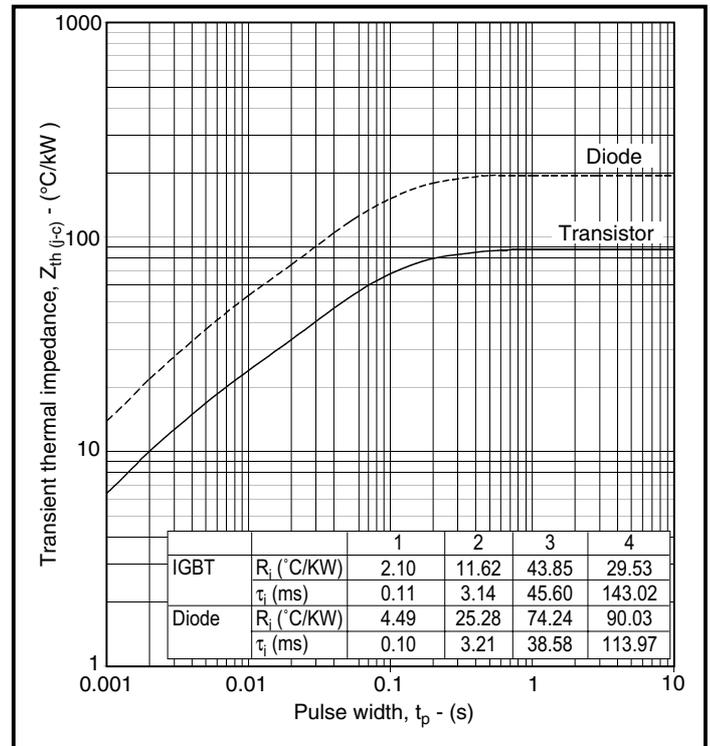


Fig. 6 Typical switching energy vs gate resistance


**Fig. 7 Diode typical forward characteristics**

**Fig. 8 Reverse bias safe operating area**

**Fig. 9 Diode reverse bias safe operating area**

**Fig. 10 Transient thermal impedance**

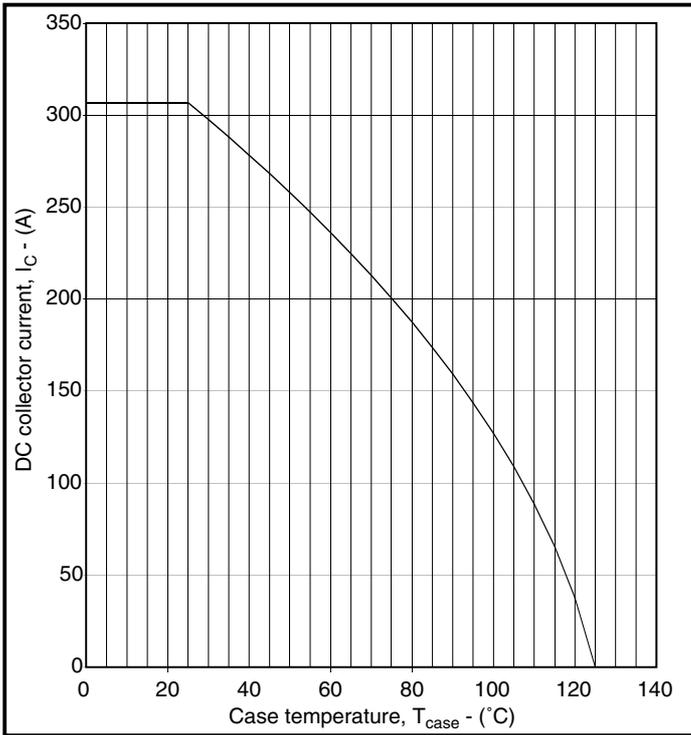


Fig. 11 DC current rating vs case temperature

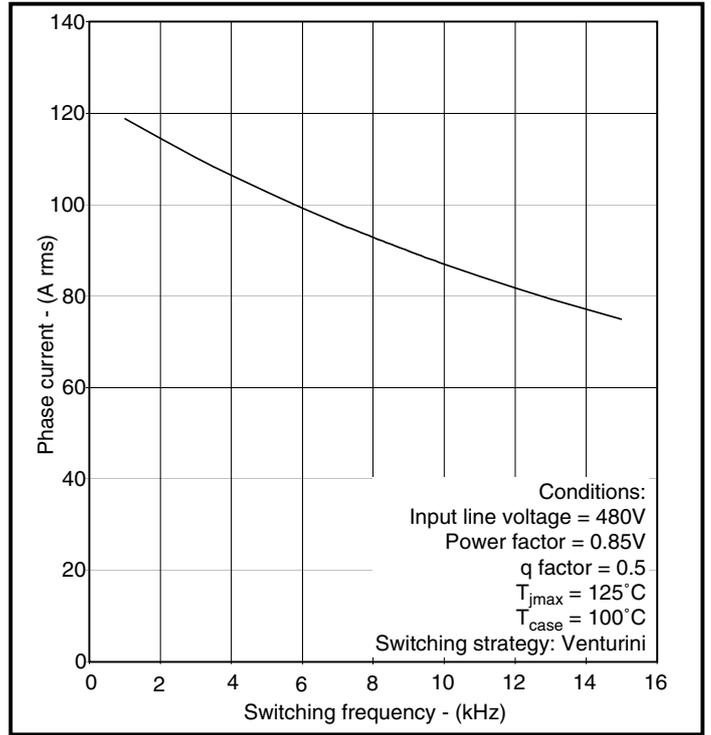
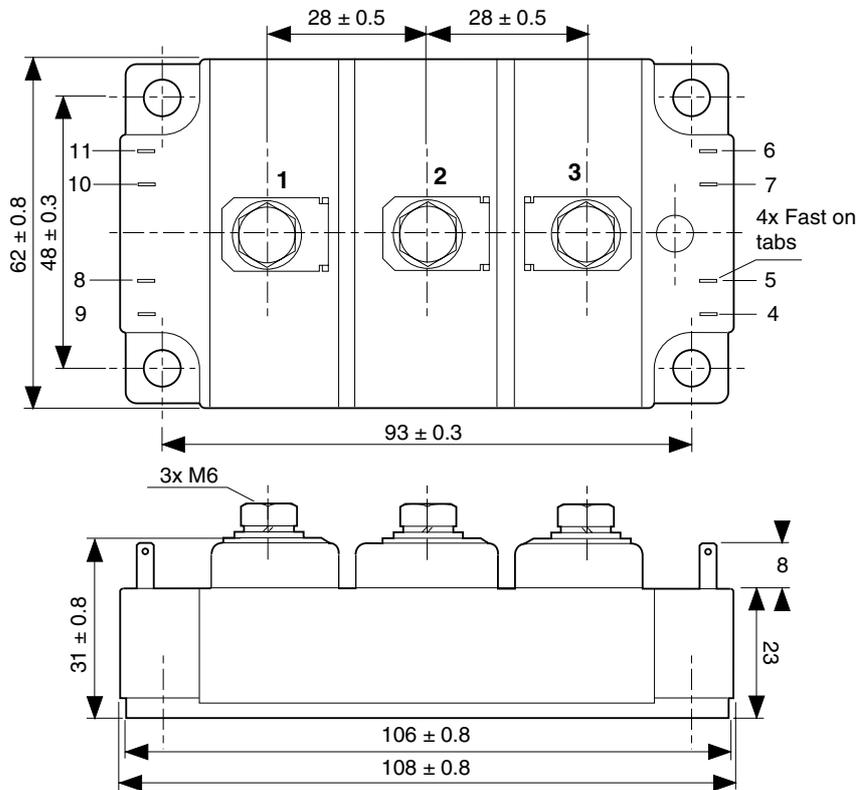


Fig. 12 Matrix converter phase current vs switching frequency

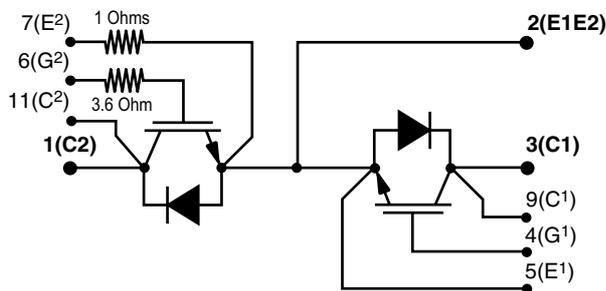
**PACKAGE DETAILS**

For further package information please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Nominal weight: 270g  
 Recommended fixings for mounting: M6  
 Recommended mounting torque: 5Nm (44lbs.ins)  
 Recommended torque for electrical connections (M6): 5Nm (44lbs.ins)

**Module outline type code: M**



**Note:** There are 2 auxiliary emitter connections (pins 5 and 7). If these are connected together externally, it is recommended that a proportion of the gate resistance (20% typically) is included in the auxiliary emitter to prevent large circulating currents.

**Fig. 13 Module outline**

Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures.

## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

## HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



<http://www.dynexsemi.com>

**e-mail: [power\\_solutions@dynexsemi.com](mailto:power_solutions@dynexsemi.com)**

HEADQUARTERS OPERATIONS  
**DYNEX SEMICONDUCTOR LTD**  
Doddington Road, Lincoln.  
Lincolnshire. LN6 3LF. United Kingdom.  
Tel: +44-(0)1522-500500  
Fax: +44-(0)1522-500550

CUSTOMER SERVICE  
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

SALES OFFICES  
**Benelux, Italy & Switzerland:** Tel: +33 (0)1 64 66 42 17. Fax: +33 (0)1 64 66 42 19.  
**France:** Tel: +33 (0)2 47 55 75 52. Fax: +33 (0)2 47 55 75 59.  
**Germany, Northern Europe, Spain & Rest Of World:** Tel: +44 (0)1522 502753 / 502901.  
Fax: +44 (0)1522 500020  
**North America:** Tel: (440) 259-2060. Fax: (440) 259-2059. Tel: (949) 733-3005. Fax: (949) 733-2986.

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